

ABSTRACT

MEMBER FOR SEMICONDUCTOR MANUFACTURING DEVICE

Provided is a member for semiconductor manufacturing device which hardly causes component contamination and is capable of sufficiently reducing generation of particles in a semiconductor manufacturing device. A spray coating is formed by spraying a ceramic onto a mounting member 16 of a transfer arm 1, and laser beam is irradiated to the spray coating to remelt and resolidify the ceramic composition for modification to thereby form a high-strength ceramic layer 5 made from a ceramic recrystallized material and having a net-like crack 6, whereby particles dropped out from the mounting member (16) due to external factors in a semiconductor manufacturing device 50 are reduced to an extent not affecting a semiconductor manufacturing process.

(Fig. 2)